**ORDER DESCRIPTION**

1. **Object of the contract**

The subject of the order is the supply of semiconductors sapphire wafers listed below by name and quantity needed:

* sapphire wafers 2 psc.

1. **The scope of the subject of the contract**

A detailed description of the subject of the contract is provided in section 5 of this document.

1. **Criterion**

Offers will be evaluated according to a point scale with a maximum number of points of 100.

| Criterion | Maximum number of points S | Method of awarding points |
| --- | --- | --- |
| Net Price (P) | 100 | S x Pmin/Pi |

Where:

* Pi – net price of goods - for the given offer
* Pmin - the minimum net price for the ordered goods from all offers submitted
* S – number of points

The final score will be calculated by adding up the partial components and then rounded to two decimal places (rounded from "5" up).

1. **Deadline for completion of the order**

**As soon as possible, no later than 10 weeks from the date of placing the order.**

Deadline for completion of the order includes readiness to hand over the goods to the Ordering Party, which complies with application of the EXW Incoterms2020 principle. According to the EXW (ex works) principle, the moment of delivery of the goods is considered to be the moment of placing the goods at the disposal of the buyer at a place indicated by the supplier (factory, plant etc.).

**The Ordering Party shall accept application of other Incoterms2020 principles (such as FCA, DAP etc.), on condition that the Contractor will meet the deadline for completion, as referred to above.**

1. **Parameters**

**5.1 Detailed scope of the subject**

| Product name |  | Parametrer | Specification |
| --- | --- | --- | --- |
| **Sapphire wafers** | Diameter 200 mm +/- 0.1 mm  Thickness: 1.25 mm +/- 0.1mm | Growth method | Kyropolos |
| Orientation: | C-Plane |
| Surface Finish: | Front side polished - quality 40-60  Back side as lapped |